

(12)
United States Design Patent
Leifeste et al.

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(45) **Date of Patent:** **** Mar. 2, 2021**

(54) **HANDHELD SEMICONDUCTOR WAFER HANDLING TOOL**

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(73) Assignee: **Raytheon Company**, Waltham, MA (US)

(**) Term: **15 Years**

(21) Appl. No.: **29/690,034**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**; D8/14

(58) **Field of Classification Search**
USPC D8/14, 51, 107; D13/182
CPC H01L 21/67742; H01L 21/68707; B25J 15/0014
See application file for complete search history.

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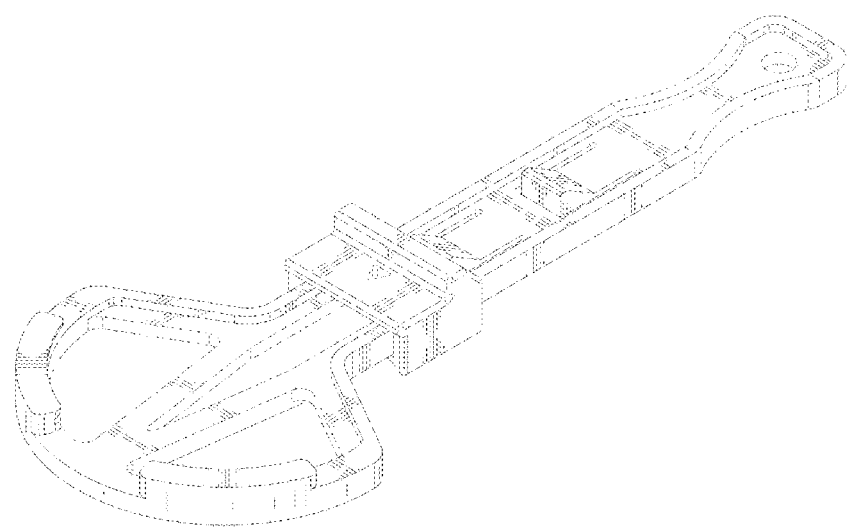
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Primary Examiner — Philip S Hyder

(57) **CLAIM**
The ornamental design for a handheld semiconductor wafer handling tool, as shown and described.

DESCRIPTION
FIG. 1 is a top front perspective view of a handheld semiconductor wafer handling tool with a movable clip in a first position;
FIG. 2 is a front end view of the handheld semiconductor wafer handling tool of FIG. 1;
FIG. 3 is a back end view of the handheld semiconductor wafer handling tool of FIG. 1;
FIG. 4 is a right side view of the handheld semiconductor wafer handling tool of FIG. 1;
FIG. 5 is a left side view of the handheld semiconductor wafer handling tool of FIG. 1;
FIG. 6 is a top view of the handheld semiconductor wafer handling tool of FIG. 1;
FIG. 7 is a bottom view of the handheld semiconductor wafer handling tool of FIG. 1;
FIG. 8 is a bottom rear perspective view of the handheld semiconductor wafer handling tool of FIG. 1;
FIG. 9 is a top front perspective view of the handheld semiconductor wafer handling tool of FIG. 1 with the movable clip in a second position; and,
FIG. 10 is a perspective view of the handheld semiconductor wafer handling tool of FIG. 1 with a semiconductor wafer. The broken line portions of the semiconductor wafer handling tool in FIGS. 1 through 10 are not considered part of the claimed design. Additional broken lines in FIG. 10 are provided for purposes of environment and form no part of the claimed design.

1 Claim, 8 Drawing Sheets



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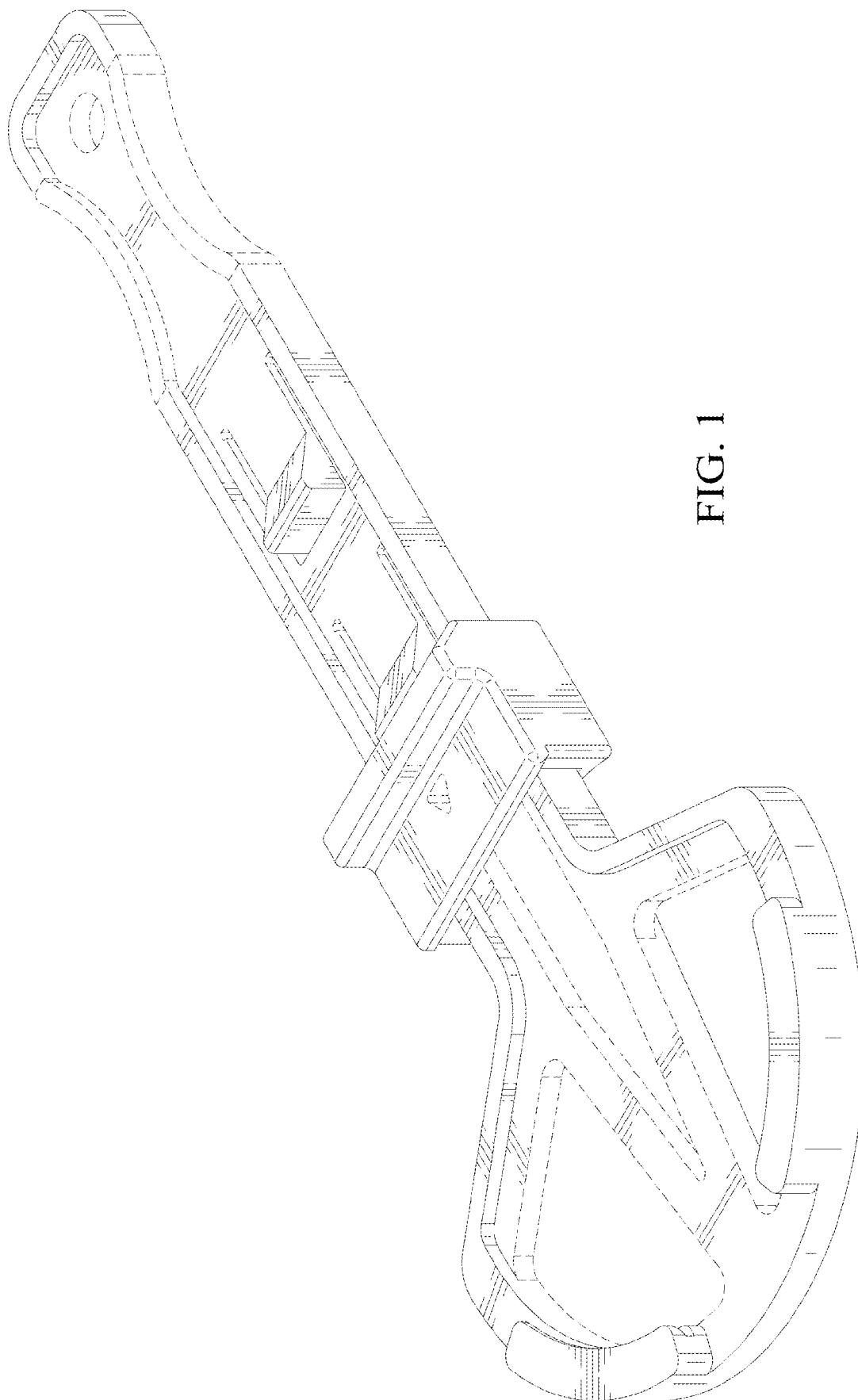


FIG. 1

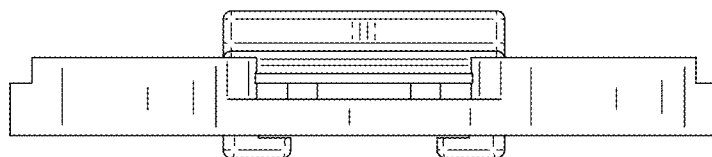


FIG. 2

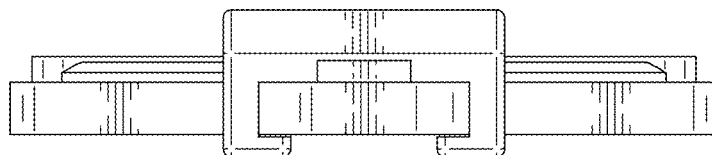


FIG. 3

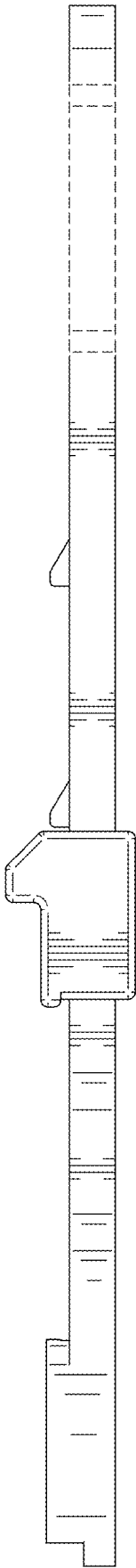


FIG. 4

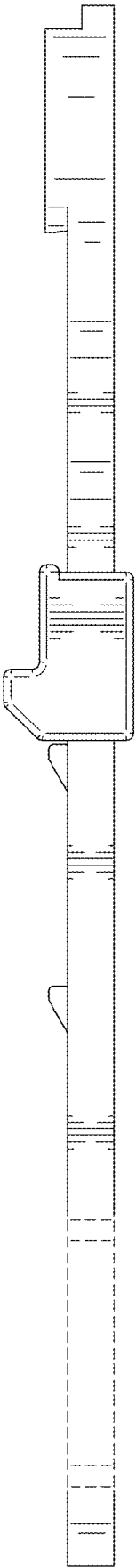


FIG. 5

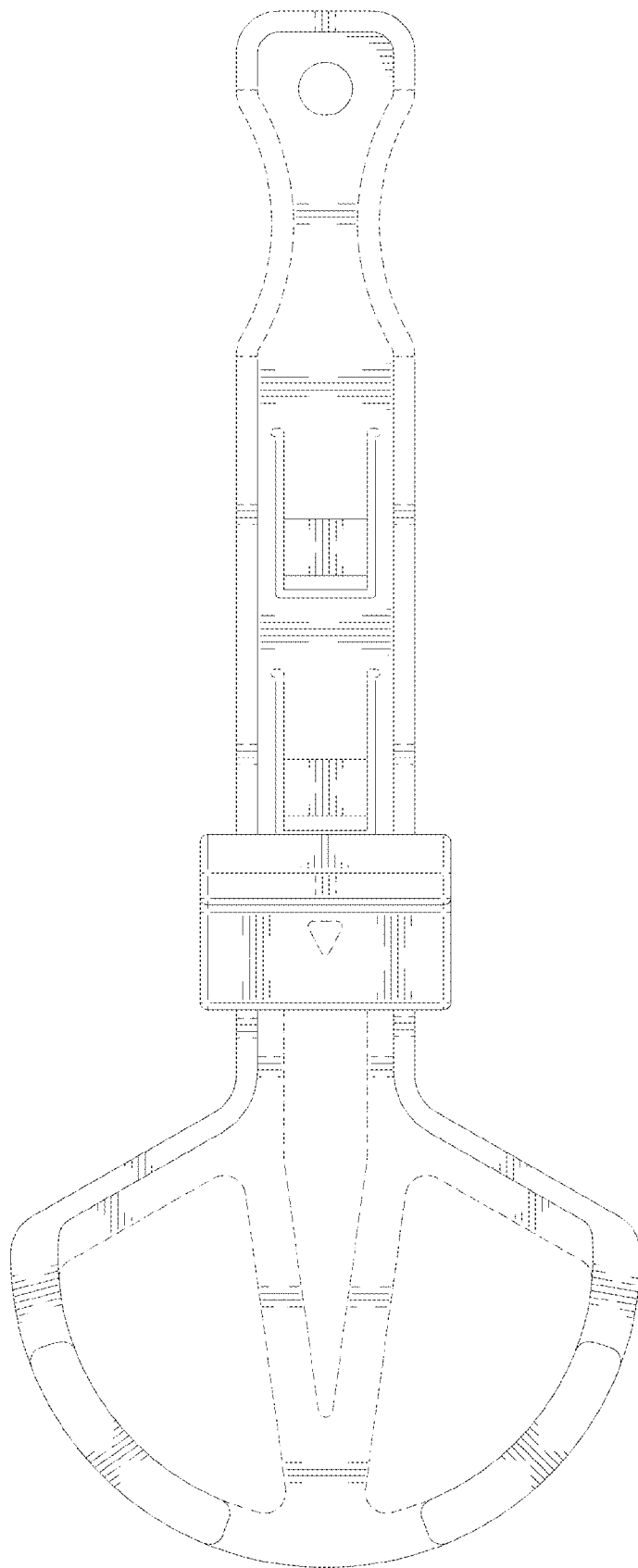


FIG. 6

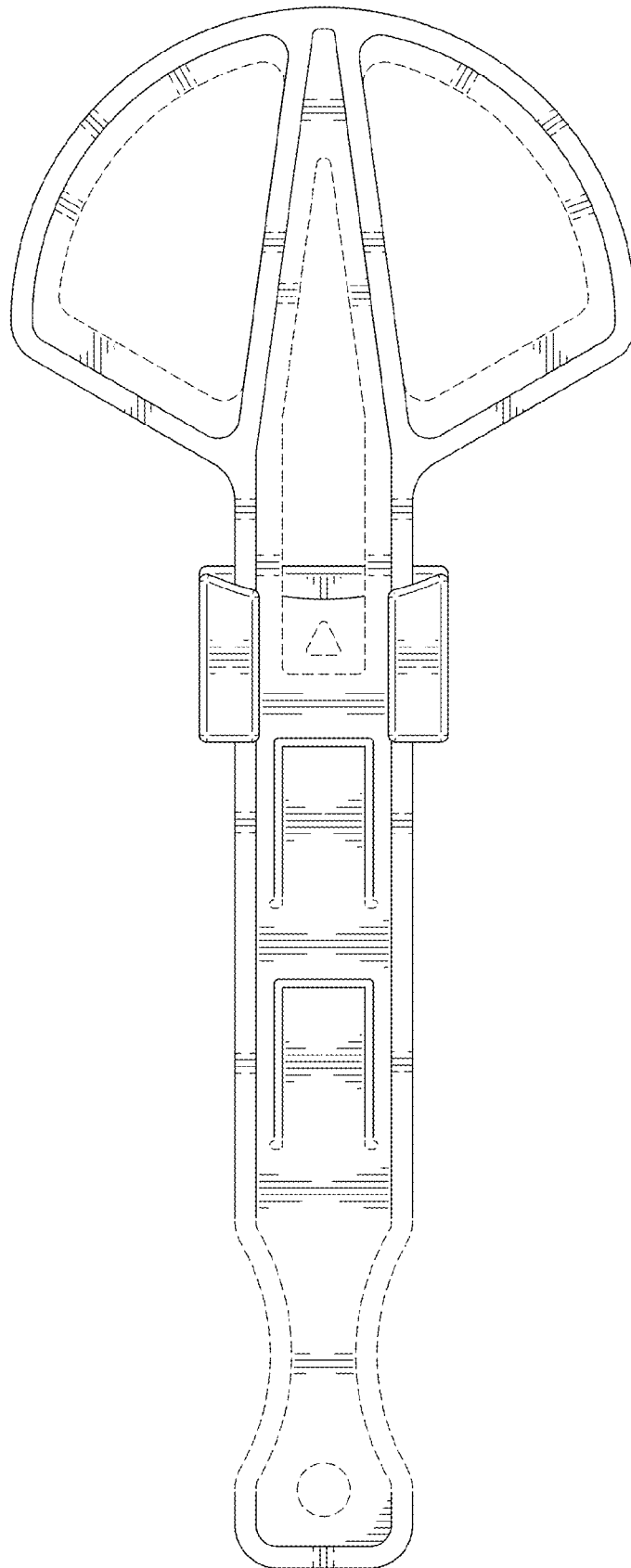


FIG. 7

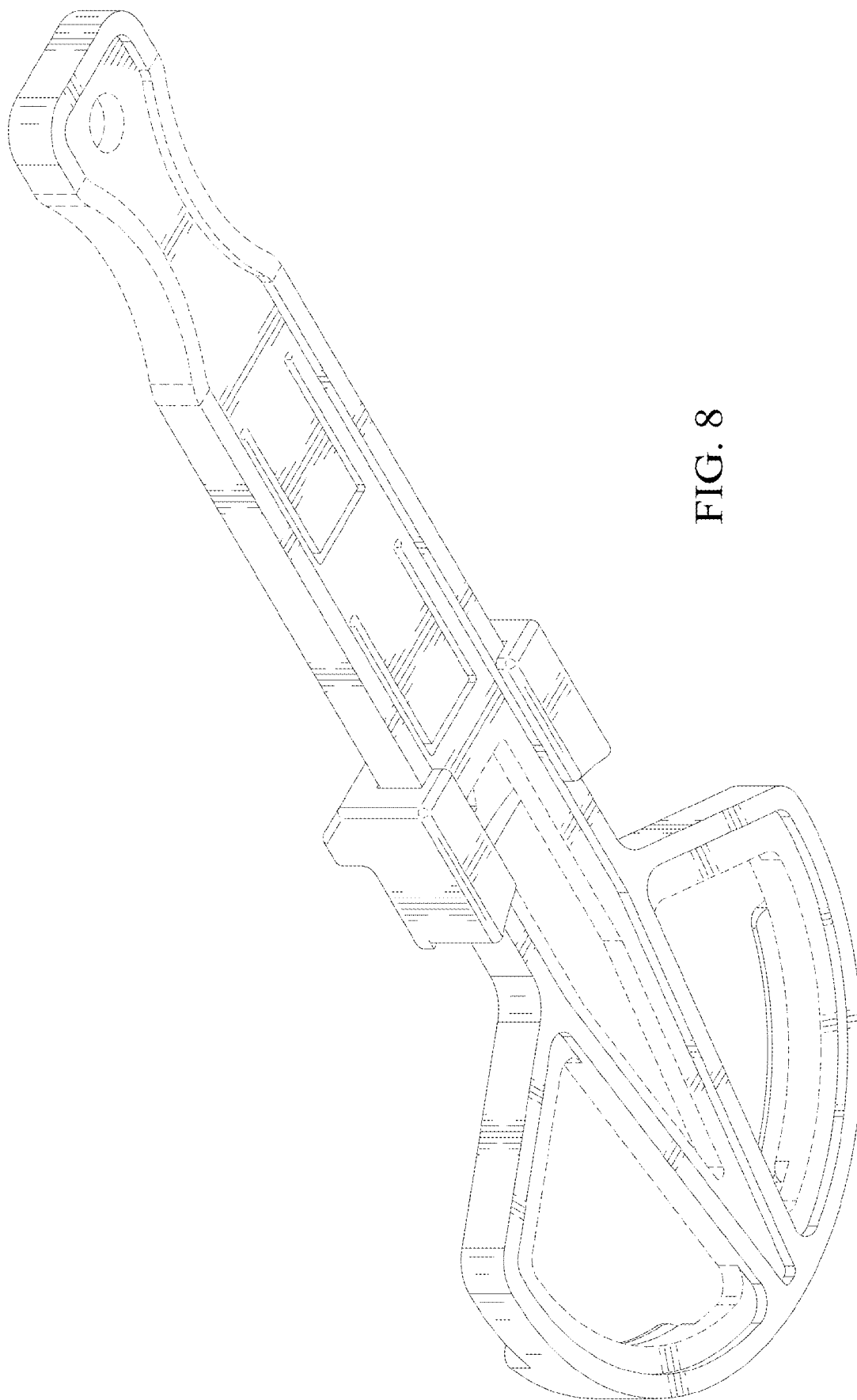


FIG. 8

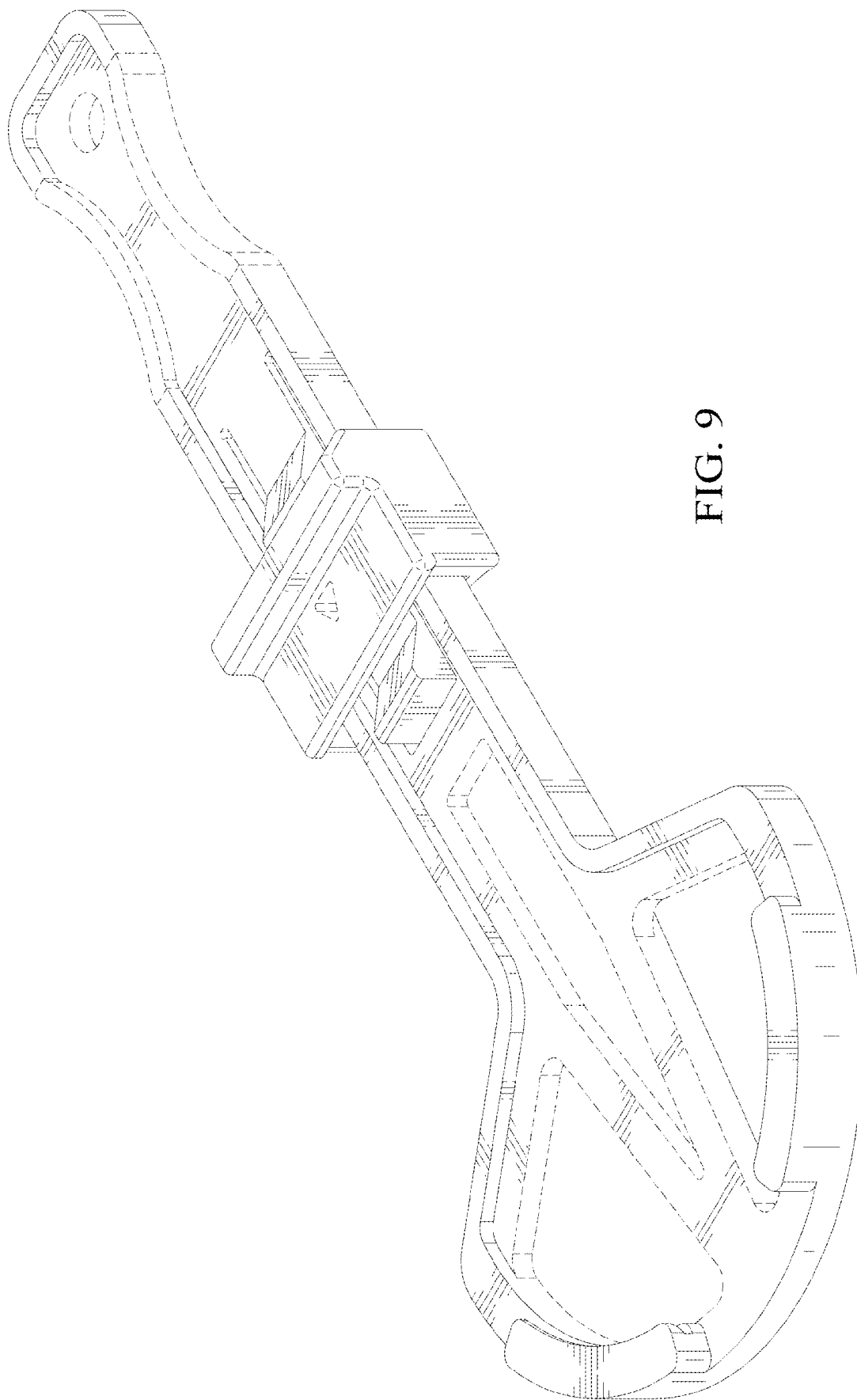


FIG. 9

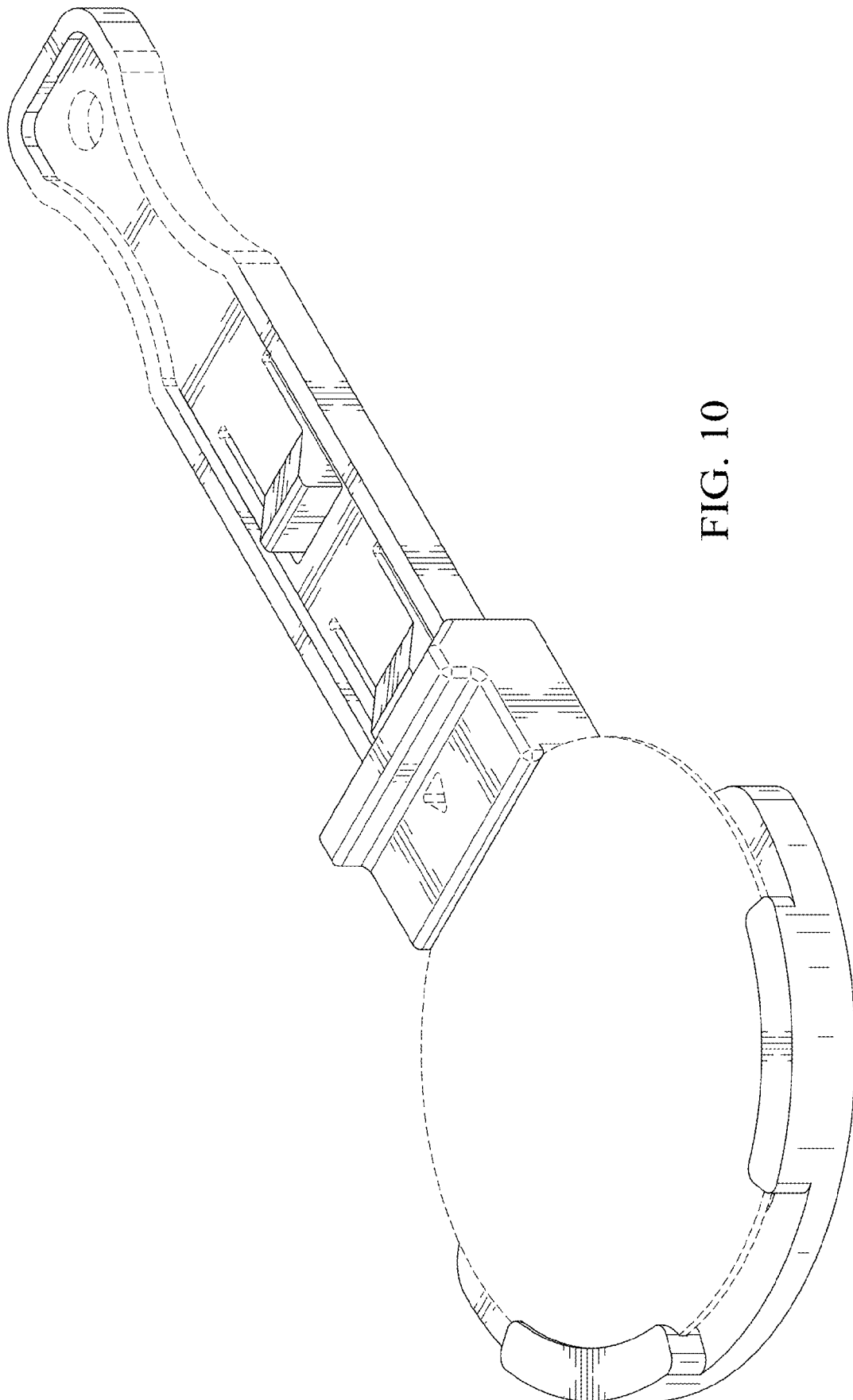


FIG. 10